

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A thermosetting resin composition comprising:

a polyimide resin component (A) containing at least one polyimide resin;

an amine component (B) containing at least one amine;

an epoxy resin component (C) containing at least one epoxy resin; and

an imidazole component (D) containing at least one imidazole.

2. (original): The thermosetting resin composition according to claim 1, wherein the mass ratio of the content of the polyimide resin component (A) to the total content of the amine component (B) and the epoxy resin component (C) is in the range of 0.4 to 2.0.

3. (original): The thermosetting resin composition according to claim 2, wherein the epoxy resin component (C) contains a crystalline epoxy resin.

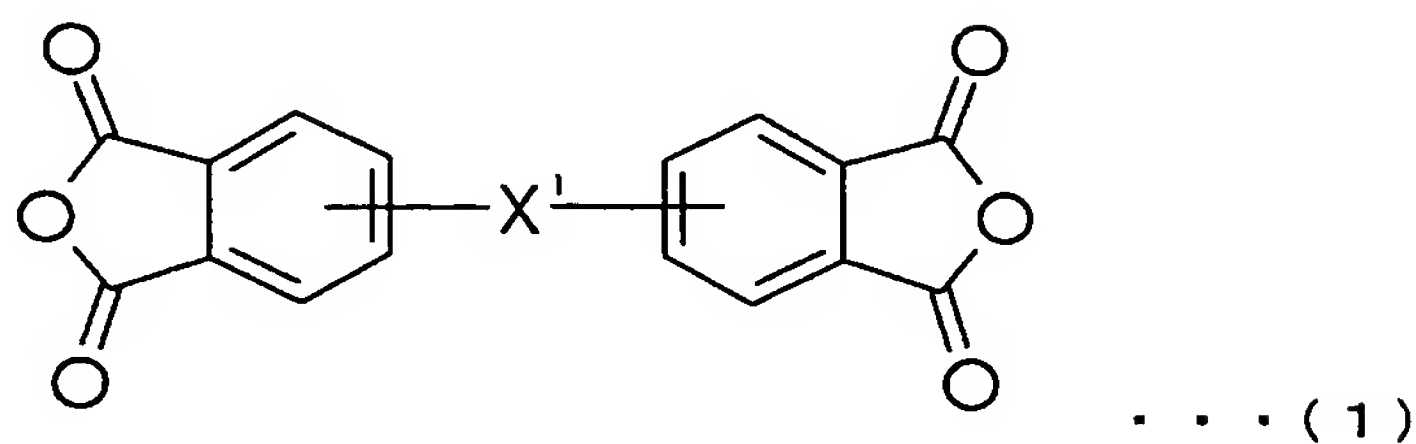
4. (original): The thermosetting resin composition according to claim 3, wherein the melting point of the crystalline epoxy resin is in the range of 60°C to 220°C.

5. (currently amended): The thermosetting resin composition according to claim 1~~any one of claims 1 to 4~~, wherein the thermosetting resin composition is in a semi-cured state and has a minimum melt viscosity in the range of 100 poise to 50,000 poise in the temperature range of 60°C to 200°C.

6. (currently amended): The thermosetting resin composition according to claim 1~~any one of claims 1 to 5~~, wherein the ratio of the number of moles of active hydrogen contained in the amine component (B) to the number of moles of epoxy groups in the epoxy resin contained in the epoxy resin component (C) is in the range of 0.4 to 2.0.

7. (currently amended): The thermosetting resin composition according to claim 1~~any one of claims 1 to 6~~, wherein the amine component (B) contains an aromatic diamine having a molecular weight of 300 or more.

8. (currently amended): The thermosetting resin composition according to claim 1~~any one of claims 1 to 7~~, wherein the at least one polyimide resin contained in the polyimide resin component (A) is prepared by reacting a diamine component (A-2) containing at least one diamine and an acid dianhydride (A-1) containing at least one acid dianhydride having a structure represented by general formula (1):



(wherein X¹ represents a divalent group selected from the group consisting of -O-, -CO-, -O-X²-O-, and -COO-X²-OCO-, wherein X² represents a divalent organic group).

9. (currently amended): A laminate comprising at least one resin layer including the thermosetting resin composition according to claim 1 ~~any one of claims 1 to 8~~.

10. (currently amended): A circuit board comprising the thermosetting resin composition according to claim 1 ~~any one of claims 1 to 8~~.